# **SD05T1 Series**

Preferred Device

# **Transient Voltage Suppressor Diode**

## SOD-323 Diodes for ESD Protection

These TVS diodes are designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. These devices are ideal for situations where board space is at a premium.

#### **Specification Features:**

- Steady State Power Routing of 200 mW
- Peak Power 350 W (8 × 20 μs)
- Low Leakage
- Cathode Indicated by Polarity Band
- Package Weight: 4.507 mg/wmt
- Meets IEC61000-4-2 Level 4, 15 kV (Air), 8 kV (Contact)
- Meets IEC6100-4-4 Level 4, 40 A
- Meets IEC6100-4-5 (Lightning), 24 A
- Meets 16 kV Human Body Model ESD Requirements
- Pb–Free Packages are Available

#### **Mechanical Characteristics:**

CASE: Void-free, transfer-molded, thermosetting plastic Epoxy Meets UL 94, V–0 LEAD FINISH: 100% Matte Sn (Tin) MOUNTING POSITION: Any QUALIFIED MAX REFLOW TEMPERATURE: 260°C Device Meets MSL 1 Requirements

Use the Device Number to order the 7 inch/3,000 unit reel. Replace the "T1" with "T3" in the Device Number to order the 13 inch/10,000 unit reel.

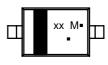


## **ON Semiconductor®**

http://onsemi.com







**MARKING DIAGRAM** 

SOD-323 CASE 477 STYLE 1

Μ

xx = Specific Device Code ZA = SD05T1

- ZC = SD12T1
- = Month Code
- = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
SD05T1	SOD-323	3000/Tape & Reel
SD05T1G	SOD-323 (Pb-Free)	3000/Tape & Reel
SD12T1	SOD-323	3000/Tape & Reel
SD12T1G	SOD-323 (Pb-Free)	3000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 20 $\mu$ s (Note 1) @ T <sub>L</sub> $\leq$ 25°C	P <sub>pk</sub>	350	Watts
IEC 61000–4–2 (ESD) Air Contact		±15 ±8.0	kV
IEC 61000–4–4 (EFT)		40	А
ESD Voltage (Human Body Model (HBM) Waveform per IEC 61000–4–2)	V <sub>PP</sub>	30	kV
Total Power Dissipation on FR–5 Board (Note 2) @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	200 1.6	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{ hetaJA}$	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

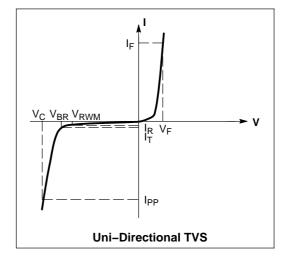
\*Other voltages may be available upon request.

1. Nonrepetitive current pulse, per Figure 6. 2.  $FR-5 = 1.0 \times 0.75 \times 0.62$  in.

#### **ELECTRICAL CHARACTERISTICS**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Symbol	Parameter						
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current						
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>						
V <sub>RWM</sub> Working Peak Reverse Voltage							
I <sub>R</sub>	Maximum Reverse Leakage Current @ $V_{\mbox{RWM}}$						
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>						
IT	Test Current						
١ <sub>F</sub>	Forward Current						
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>						



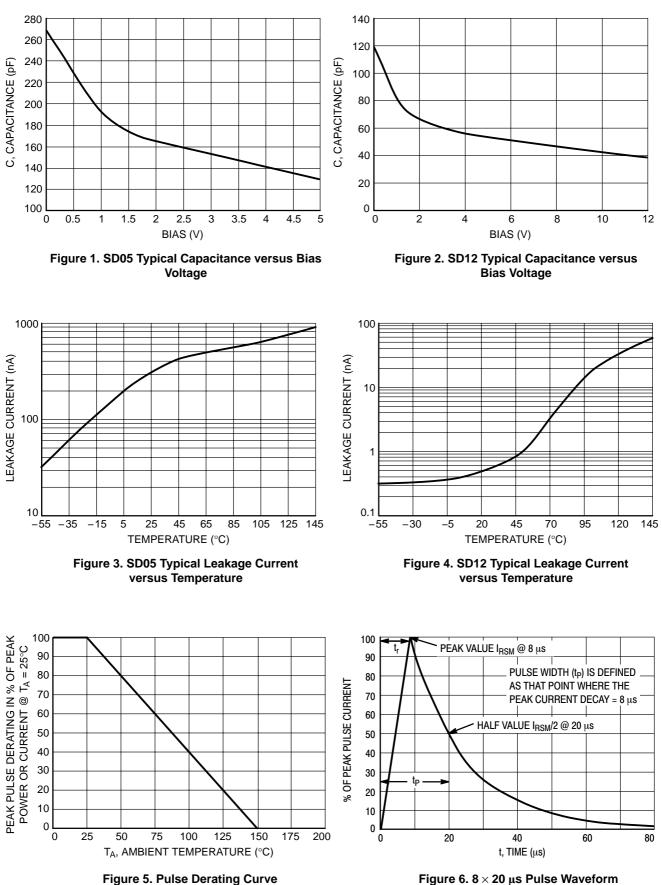
#### **ELECTRICAL CHARACTERISTICS**

			V <sub>BR</sub> , Breakdown Voltage (V)			V <sub>C</sub> @ I <sub>PP</sub> = 5 A	Max I <sub>PP</sub>	V <sub>C</sub> @ Max I <sub>PP</sub>	Max Capacitance (pF)
Device	V <sub>RWM</sub> (V)	I <sub>R</sub> @ V <sub>RWM</sub> (μΑ)	Min	Мах	I <sub>T</sub> mA	(Note 3) (V)	(Note 3) (A)	(Note 3) (V)	V <sub>R</sub> = 0 V f = 1.0 MHz
SD05T1, G	5.0	10	6.2	7.3	1.0	9.8	24	14.5	350
SD12T1, G	12	1.0	13.3	15.75	1.0	19	15	25	150

3.  $8 \times 20 \ \mu s$  pulse waveform.

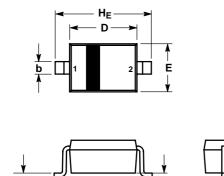
## SD05T1 Series

### **TYPICAL CHARACTERISTICS**



#### PACKAGE DIMENSIONS

SOD-323 CASE 477-02 **ISSUE G** 



1

NOTE 5

С

NOTE 3



Δ1

NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS. LEAD THICKNESS SPECIFIED PER L/F DRAWING 2. 3. WITH SOLDER PLATING. DIMENSIONS A AND B DO NOT INCLUDE MOLD

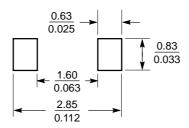
4. FLASH, PROTRUSIONS OR GATE BURRS. 5. DIMENSION L IS MEASURED FROM END OF

RADIUS.

	MIL	LIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.031	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3	0.15 REF			0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016	
С	0.089	0.12	0.177	0.003	0.005	0.007	
D	1.60	1.70	1.80	0.062	0.066	0.070	
E	1.15	1.25	1.35	0.045	0.049	0.053	
L	0.08			0.003			
HE	2.30	2.50	2.70	0.090	0.098	0.105	

STYLE 1: PIN 1. CATHODE 2. ANODE

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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